

### **Product Change Notification / RMES-19ZBNI141**

D	2	ŧ	Δ	•
ப	а	L	ᆫ	

29-May-2021

# **Product Category:**

Memory

# **PCN Type:**

Manufacturing Change

## **Notification Subject:**

CCB 4685 Initial Notice: Qualification of Ag on lead (Inner Lead Plating) material for selected SST26WF080B and SST26WF040B device families available in 8L UDFN (2x3x0.55mm) package.

## **Affected CPNs:**

RMES-19ZBNI141\_Affected\_CPN\_05292021.pdf RMES-19ZBNI141\_Affected\_CPN\_05292021.csv

### **Notification Text:**

PCN Status:Initial notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**Qualification of Ag on lead (Inner Lead Plating) material for selected SST26WF080B and SST26WF040B device families available in 8L UDFN (2x3x0.55mm) package.

#### Pre and Post Change Summary:

	Pre Change Post Change			
Assembly Site	UTAC Thai Limited (NSEB) UTAC Thai Limited (NSEB)			
Wire material	Au Au			
Die attach material	HR-5104 (DAF)	HR-5104 (DAF)		

Molding compound material	G700LTD	G700LTD				
Lead frame material	EFTEC-64T	EFTEC-64T				
Lead frame material	See Pre and Post Change Summary for comparison					
Inner Lead Plating	NiPdAu	Ag				
(Bond Finger)	(Pd Custom Plating)	(Ag on lead only)				
Lead Finish Plating	Matte Tin	Matte Tin				

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying Ag on lead (Inner Lead Plating) material.

**Change Implementation Status:**In Progress

Estimated Qualification Completion Date: October 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

### Time Table Summary:

	May 2021					October 2021					
Workweek	19	20	2 1	22	23	^	41	42	43	44	45
Initial PCN Issue Date				Х							
Qual Report Availability											Χ
Final PCN Issue Date											Χ

#### Method to Identify Change:

Traceability code

 $\textbf{Qualification Plan:} Please open the attachments included with this PCN labeled as PCN\_\#\_Qual\_Plan.$ 

**Revision History:** 

May 28, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

PCN\_RMES-19ZBNI141\_Qual\_Plan.pdf PCN\_RMES-19ZBNI141\_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

RMES-19ZBNI141-CCB~4685~Initial~Notice: Qualification~of~Ag~on~lead~(Inner~Lead~Plating)~material~for~selected~SST26WF080B~and~SST26WF040B~device~families~available~in~8L~UDFN~(2x3x0.55mm)~package.

Affected Catalog Part Numbers (CPN)

SST26WF080BT-104I/NP SST26WF080BAT-104I/NP SST26WF040BT-104I/NP SST26WF040BAT-104I/NPINTC

Date: Friday, May 28, 2021